

Li-Ion Power Gauge™ Module

Features

- Complete bq2050 Power Gauge solution for Li-Ion battery packs
- Battery information available over a single-wire bidirectional serial port
- Battery state-of-charge monitoring for 2- to 4-cell series applications
- On-board regulator allows direct connection to the battery
- “L” version includes push-button activated LEDs to display state-of-charge information
- Nominal capacity pre-configured
- Compact size for battery pack integration

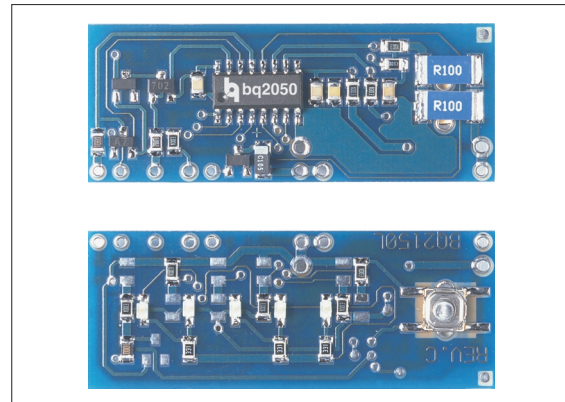
General Description

The bq2150 Power Gauge Module provides a complete and compact solution for capacity monitoring of Li-Ion battery packs. Designed for battery pack integration, the bq2150 incorporates a bq2050 Gas Gauge IC, a current sense resistor, and all other components necessary to accurately monitor and display the capacity of 2 to 4 series cells.

The bq2150L includes five LEDs to display remaining capacity in 20% increments of the learned capacity. The LEDs are activated with the onboard push-button switch.

Contacts are provided on the bq2150 for direct connection to the battery stack (BAT+, BAT-) and the serial communications port (DQ). The RBI input provides backup power to the bq2050 in the event that the cells are removed or the battery is turned off. The bq2150 has a 1µF capacitor onboard connected to RBI to supply backup power for about an hour. In battery packs that use high-side FETs to control the charge/discharge of the Li-Ion cells, the RBI input can be wired to a single cell to provide prolonged data retention times. The SD input allows an external signal (active low) to turn the bq2050 IC off to minimize internal current consumption of the battery pack and maximize storage life of the pack in the system. When turned off, the bq2050 is non-functional, and the RBI power source maintains register information. Please refer to the bq2050 data sheet for the specifics on the operation of the gas gauge.

Unitrode configures the bq2150 based on the information requested in Table 1. The configuration defines the number of series cells, the nominal battery pack capacity, and the Li-Ion battery type (coke or graphite anode). Figure 1 shows how the module connects to the cells.



A module development kit is also available for the bq2150. The bq2150B-KT or the bq2150LB-KT includes one configured module and the following:

- 1) An interface board that allows connection to the serial port of an AT-compatible computer.
- 2) Menu-driven software to display charge/discharge activity and to allow user interface to the bq2050 from any standard DOS PC.
- 3) Source code for the TSR.

Pin Descriptions

| | |
|-----------|--|
| P1 | DQ/Serial Communications port |
| P2 | No connect |
| P3 | BAT+/Battery positive/pack positive |
| P4 | SD/Shutdown |
| P5 | RBI/Register backup input |
| P6 | GND/Ground |
| P7 | PACK-/Pack negative |
| P8 | BAT-/Battery negative |

bq2150

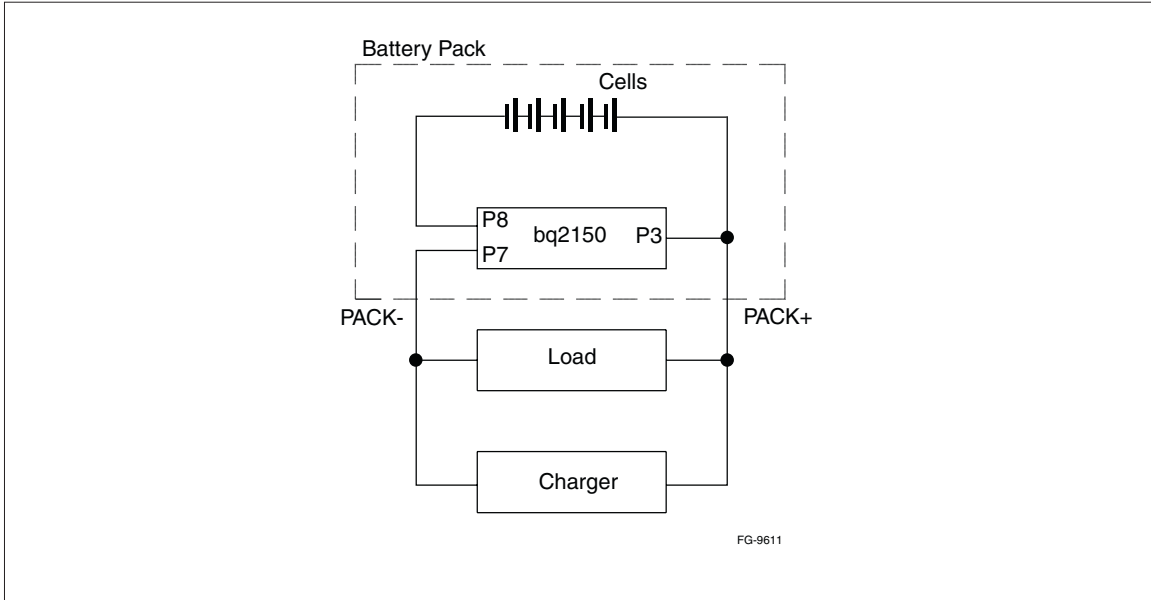


Figure 1. Module Connection Diagram

Table 1. bq2150 Module Configuration

Customer Name: _____

Contact: _____ Phone: _____

Address: _____

Sales Contact: _____ Phone: _____

Number of series battery cells (2-4) _____

Coke or graphite cell anode _____

Battery pack capacity (mAh) _____

Discharge rate into load (3.0A max) Min. _____ Avg. _____ Max. _____

Charge rate (3.0A max) _____

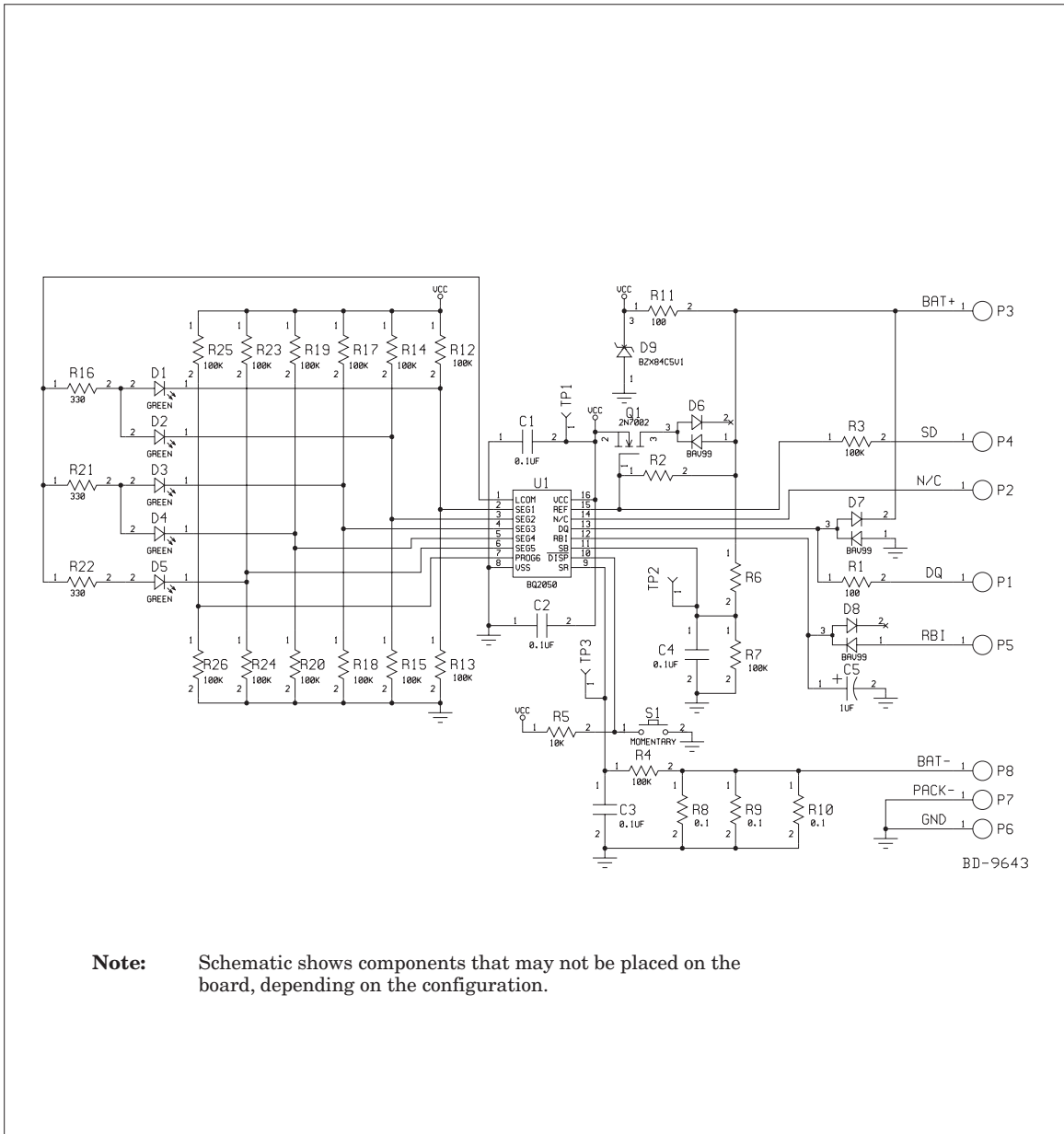
Nominal Available Capacity after reset
(Programmed Capacity or Zero) _____

Self-discharge compensation (Y/N) _____

LEDs and switch (Y/N) _____

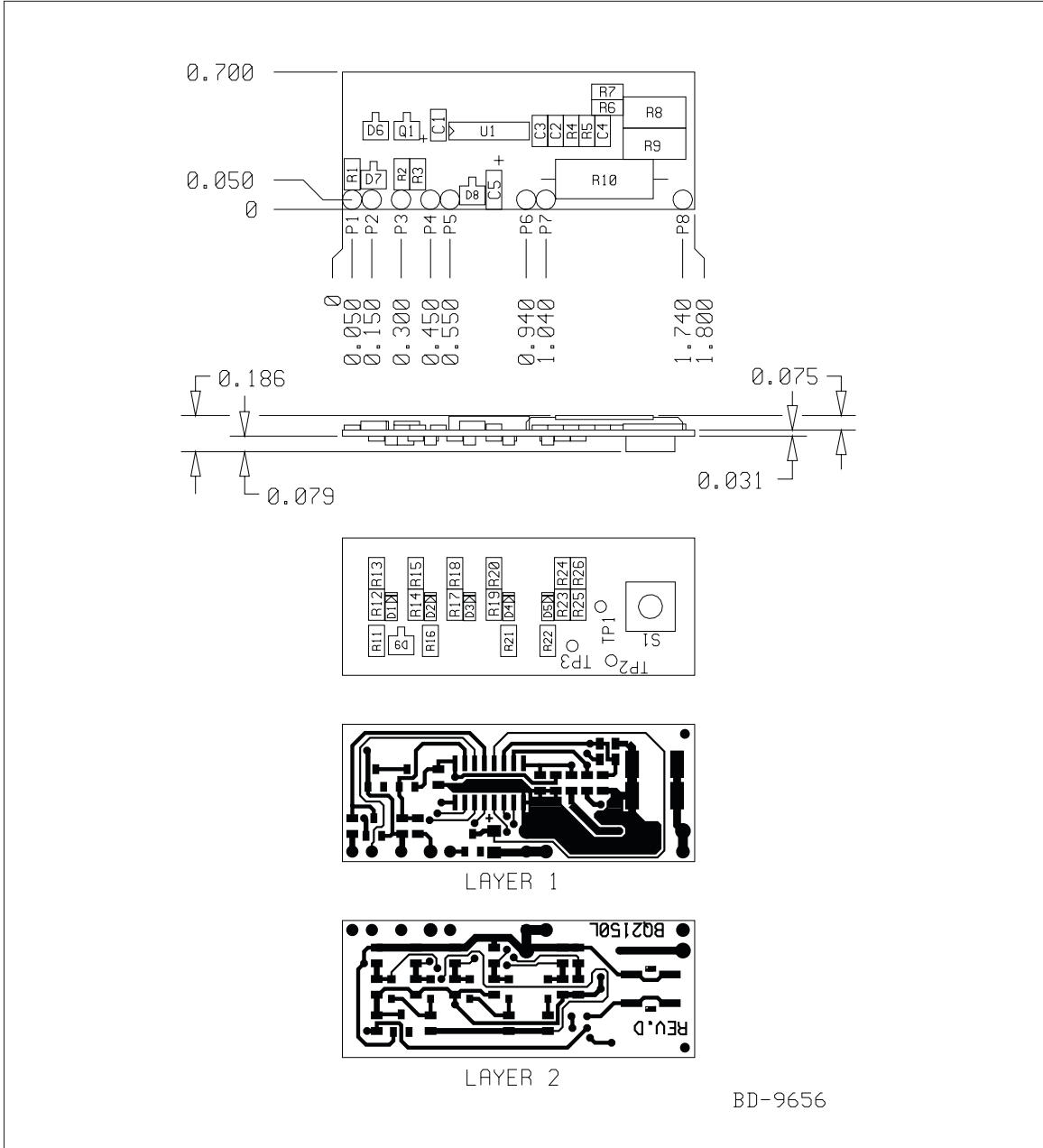
FAE Approval: _____ Date: _____

bq2150 Schematic



bq2150

bq2150 Board



Absolute Maximum Ratings

| Symbol | Parameter | Minimum | Maximum | Unit | Conditions |
|----------------|---|---------|---------|------|------------------------------|
| VCC | Relative to VSS | -0.3 | +7.0 | V | bq2050 |
| All other pins | Relative to VSS | -0.3 | +7.0 | V | bq2050 |
| PSR | Continuous sense resistor power dissipation | - | 3 | W | Thru-hole sense resistor |
| | | - | 1 | W | Surface-mount sense resistor |
| ICHG | Continuous charge/discharge current | - | 3.0 | A | |
| TOPR | Operating temperature | 0 | +70 | °C | Commercial |
| TSTR | Storage temperature | -40 | +85 | °C | |

Note: Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

DC Electrical Characteristics (T_A = TOPR)

| Symbol | Parameter | Minimum | Typical | Maximum | Unit | Conditions/Notes |
|-------------------|--|-----------|----------------|----------------|-----------------|-----------------------|
| NumCell | Number of series cells in battery pack | 2 | - | 4 | - | |
| BAT+ | Positive terminal of pack | GND | NumCell * 3.6V | NumCell * 5.4V | V | |
| BAT- | Negative terminal of pack | GND - 0.3 | - | GND+2.0 | V | |
| ICC | Supply current at BAT1P terminal (no external loads) | - | 200 | 300 | μA | |
| R _{DQ} | Internal pull-down | 500k | - | - | Ω ¹ | |
| I _{OL} | Open-drain sink current DQ | - | - | 5.0 | mA ¹ | |
| V _{OL} | Open-drain output low, I _{OL} DQ | - | - | 0.5 | V ¹ | I _{OL} < 5mA |
| V _{IHDQ} | DQ input high | 2.5 | - | - | V ¹ | |
| V _{ILDQ} | DQ input low | - | - | 0.8 | V ¹ | |
| V _{OS} | Voltage offset | - | - | 150 | μV ¹ | |

Note: 1. Characterized on PCB, IC 100% tested.

bq2150

DC Voltage Thresholds (T_A = T_{OPR})

| Symbol | Parameter | Minimum | Typical | Maximum | Unit | Notes |
|-------------------|-----------------------------|---------|---------|---------|------|--|
| V _{EDVF} | Final empty warning | 1.45 | 1.47 | 1.49 | V | BAT+/(2*NumCell) ¹ |
| V _{EDV1} | First empty warning | 1.50 | 1.52 | 1.55 | V | BAT+/(2*NumCell) ¹ |
| V _{MCV} | Maximum single-cell voltage | 2.20 | 2.25 | 2.30 | V | BAT+/(2*NumCell) ¹ |
| V _{SRO} | Sense range | -300 | - | +2000 | mV | SR, V _{SR} + V _{OS} ² |
| V _{SRQ} | Valid charge | 210 | - | - | μV | V _{SR} + V _{OS} ^{2, 3} |
| V _{SRD} | Valid discharge | - | - | -200 | μV | V _{SR} + V _{OS} ^{2, 3} |

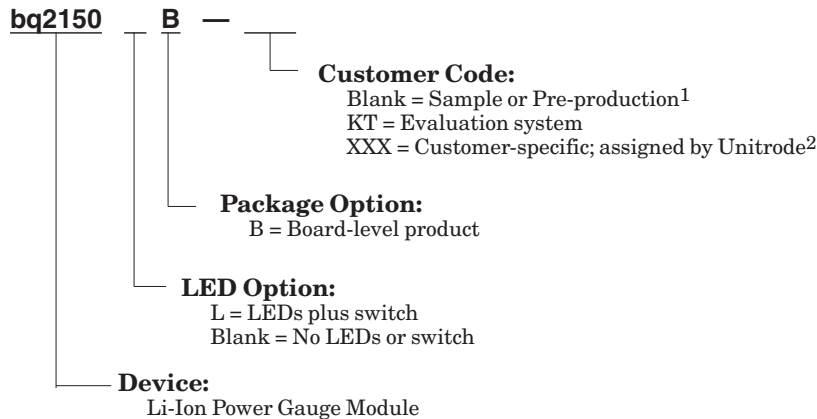
- Notes:**
1. At SB input of bq2050
 2. At SR input of bq2050.
 3. Default value; value set in DMF register.

Data Sheet Revision History

| Change No. | Page No. | Description |
|------------|----------|--|
| 1 | 2 | Updated Table 1 to include 3.0A limit |
| 1 | 5 | Added 3.0A maximum continuous charge/discharge current specification |

Note: Change 1 = May 1999 B changes from April 1999.

Ordering Information



- Notes:**
1. Requires configuration sheet (Table 1)
 2. Example production part number: bq2150LB-001

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